

ABSTRACT OF THE DISCLOSURE

A method of manufacturing the semiconductor chips comprises the steps of: pasting on a substrate an
5 adhesive sheet having a property to retain its adhesive strength prior to a processing, then lose its adhesive strength after the processing; fixing a plurality of non-defective bare chips on this adhesive sheet, with their Al electrode pad surfaces facing down; coating a resin on
10 a whole area other than the Al electrode pad surfaces of the plurality of non-defective bare chips including interspaces therebetween; applying a predetermined process to the adhesive sheet to weaken its adhesive strength of the adhesive sheet; peeling off a pseudo
15 wafer bonding non-defective bare chips; and dicing the plurality of non-defective bare chips into a discrete non-defective electronic part by cutting the pseudo wafer at a position of the resin between respective non-defective bare chips.